

**Average Weight: 14.0g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.8848</b>	<b>6.32</b>
	Silicon	7440-21-3	100.00		0.8848	
<b>Solder Bump</b>					<b>0.0154</b>	<b>0.11</b>
	Tin	7440-31-5	63.00		0.009702	
	Lead	7439-92-1	37.00		0.005698	
<b>Underfill</b>					<b>0.112</b>	<b>0.80</b>
	Silica	60676-86-0	70.00		0.0784	
	Epoxy Resin A	9003-36-5	20.00		0.0224	
	Epoxy Resin B	25068-38-6	3.00		0.00336	
	Hardener	19900-65-3	7.00		0.00784	
<b>Heat Sink</b>					<b>8.3258</b>	<b>59.47</b>
	Copper	7440-50-8	99.97		8.32330226	
	Nickel	7440-02-0	0.03		0.00249774	
<b>Heat Sink Adhesive</b>					<b>0.0007</b>	<b>0.05</b>
	Organopolysiloxane mixture	NA	100.00		0.0007	
<b>Substrate</b>					<b>3.7156</b>	<b>26.54</b>
	Copper	7440-50-8	47.61	Metal layer	1.76899716	
	Nickel	7440-02-0	0.51	Metal layer	0.01894956	
	Gold	7440-57-5	0.11	Metal layer	0.00408716	
	Glass fiber	N/A	10.35		0.3845646	
	BT (core)	N/A	27.54		1.02327624	
	Halogen fire retardant	N/A	5.25		0.195069	
	Solder mask	N/A	8.63		0.32065628	
<b>Solder Balls</b>					<b>0.9394</b>	<b>6.71</b>
	Tin	7440-31-5	63.00		0.591822	
	Lead	7439-92-1	37.00		0.347578	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/23/06	1.0	Initial Xilinx release.
7/13/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
7/20/10	1.3	Updated Heat Sink substance description.

## Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.